

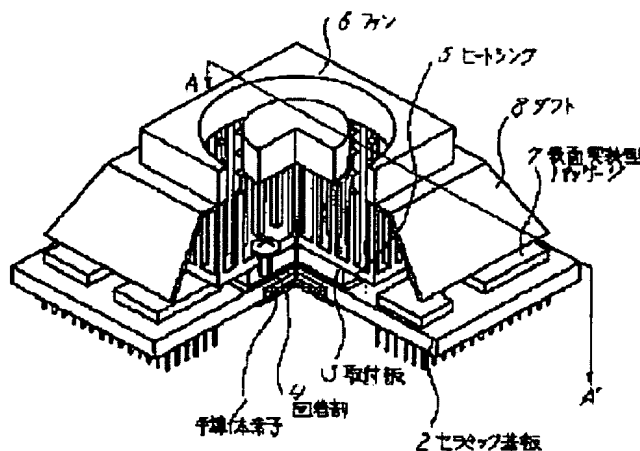
MULTI-CHIP COOLING DEVICE

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Classification:
- international: H05K7/20; H01L23/36; H01L23/467; H05K7/20;
H01L23/34; (IPC1-7): H01L23/36; H01L23/467;
H05K7/20
- european:
Application number: JP19950057879 19950317
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Abstract of JP8255855

PURPOSE: To provide a cooling structure which is capable of effectively carrying out a cooling operation for a multi-chip module, wherein semiconductor elements are easily repaired and replaced. **CONSTITUTION:** A multi-chip package is composed of a ceramic board 2, which mounts a semiconductor element 1, and semiconductor elements each encapsulated in a surface-mount package 7 formed on the surface of the ceramic board 2 opposite to its surface where the element 1 is mounted, wherein a heat sink 5 and a fan 6 are provided confronting each other, and an exhaust flow from the heat sink 5 is guided to the surface-mount packages 7 through a duct 8.



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